

**Claims**

Please add the following claims 13-18:

13. An assembly as claimed in claim 1, wherein the optical transceiver module comprises a light emitting diode and a photodiode, packaged together with supporting circuitry to form a self-contained unit.
14. An assembly as claimed in claim 13, wherein the optical transceiver module comprises a first molded lens shape over the light emitting diode and a second molded lens shape over the photodiode.
15. An assembly as claimed in claim 13, wherein the optical transceiver module is an infrared transceiver module.
16. An assembly as claimed in claim 2, wherein the side surface of the planar circuit board is a multi-faceted surface bounding the recess on three sides and leaving a fourth side open.
17. An assembly as claimed in claim 16, wherein the optical transceiver module comprises a plurality of transceiver lenses which face outwards from the open side of the recess.
18. An assembly as claimed in claim 1, wherein the optical transceiver module is surface mounted on the extended portion of the substrate.